

ABSTRACT

A method for manufacturing an electronic device includes at least a preparing step of preparing a structure (100) provided with an adhesive film (50) provided with a base material layer (10), an adhesive resin layer (A) provided on a first surface (10A) side of the base material layer (10) and used for temporarily fixing an electronic component (70), and an adhesive resin layer (B) provided on a second surface (10B) side of the base material layer (10) and in which an adhesive force is reduced by external stimuli, an electronic component (70) attached to the adhesive resin layer (A) of the adhesive film (50), and a support substrate (80) attached to the adhesive resin layer (B) of the adhesive film (50), a pre-baking step of heating the structure (100), and a sealing step of sealing the electronic component (70) with a sealing material (60).